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**(54) Title (EN):** FILM AND FILM PACKAGING CONTAINER

**(54) Title (FR):** FILM ET CONTENANT D'EMBALLAGE À BASE DU FILM

**(54) Title (JA):** フィルム及びフィルム包装容器

**(57) Abstract:**

**(EN):** A film including a layer formed from a resin composition comprising a polyamide compound (A) and a resin (B), wherein the polyamide compound (A) comprises: 25-50mol% of diamine units, including not less than 50mol% of a specific diamine unit; 25-50mol% of dicarboxylic acid units, including not less than 50mol% of a specific dicarboxylic acid unit; and 0.1-50mol% of a specific constituent unit.

**(FR):** L'invention concerne un film comprenant une couche formée d'une composition de résine comprenant un composé polyamide (A) et une résine (B), le composé polyamide (A) comprenant 25-50 % en moles d'unités diamine, ne comprenant pas

moins de 50 % en moles d'une unité diamine spécifique ; 25-50 % en moles d'unités acide dicarboxylique, ne comprenant pas moins de 50 % en moles d'une unité acide dicarboxylique spécifique ; et 0,1-50 % en moles d'une unité constitutive spécifique.

(JA): ポリアミド化合物(A)及び樹脂(B)を含有する樹脂組成物から形成される層を含むフィルムであって、該ポリアミド化合物(A)が、特定のジアミン単位を50モル%以上含むジアミン単位25～50モル%と、特定のジカルボン酸単位を50モル%以上含むジカルボン酸単位25～50モル%と、特定の構成単位0.1～50モル%とを含有する、フィルム。

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